

AIR BEARING 200MM WAFER BACK GRINDING SPINDLE

09461

FOR 8" WAFERS

FOR GRINDING SEMICONDUCTOR
AND OPTICAL MATERIALS

Speed Range	1000 - 6,000 rpm
Motor Power	4.5 kw
Air Supply Pressure	5.5 bar
Bearing Air Consumption	80 l/min
Axial Stiffness	> 13 kg/um
Axial Failure Load	> 1150 N
Radial Runout at Tool	≤ 2 um
Axial Runout at Tool	≤ 1 um
Motor Type	Brushless DC
Weight (Approx)	80 kg
Body Diameter (nominal)	165 mm

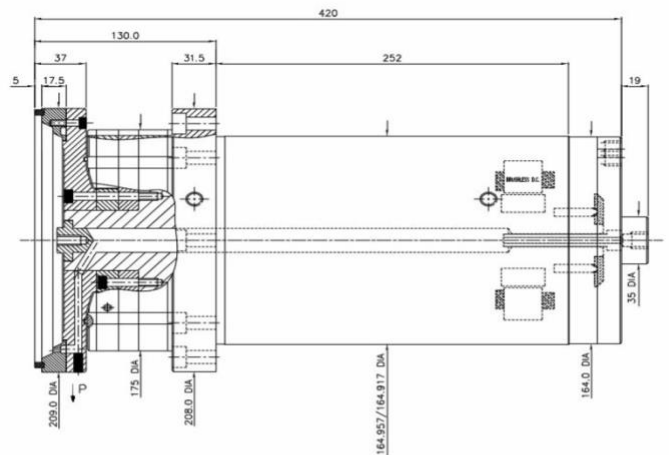
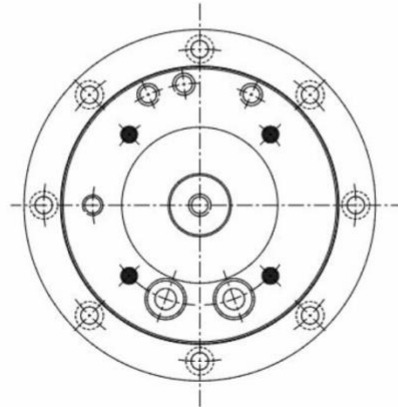
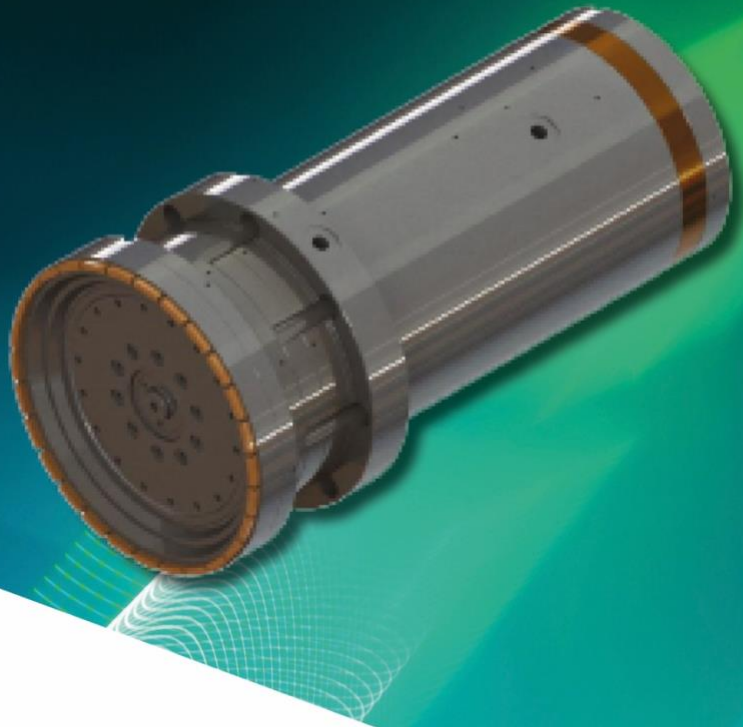
OUR DESIGN AND DEVELOPMENT
EXPERIENCE PLACES US IN THE
IDEAL POSITION TO DEVELOP NEW
AIR BEARING PRODUCTS AND
APPLICATIONS.

AVAILABLE IN A RANGE OF
CONFIGURATIONS.

ASSOCIATED SPINDLE SPEEDS TO SUIT
APPLICATION.

ENHANCED SPINDLE WITH:

- HIGH RIGIDITY
- MINIMAL VIBRATION
- LOW HEAT EXPANSION
- MINIMAL ROTATIONAL SPEED FLUCTUATION
- BI-DIRECTIONAL ROTATION
- THROUGH SHAFT COOLANT



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